



# SOT360-2

plastic, thin shrink small outline package; 20 terminals; 0.65 mm pitch; 6.5 mm x 4.4 mm x 1.05 mm body

15 December 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	TSSOP
<b>Package type industry code</b>	TSSOP20
<b>Package style descriptive code</b>	TSSOP (thin shrink small outline package)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	1-6-2016
<b>Manufacturer package code</b>	98ASH70169A

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.4	-	6.5	6.6	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	-	-	1.05	1.2	mm
e	nominal pitch	-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	20	-	



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## 2. Package outline

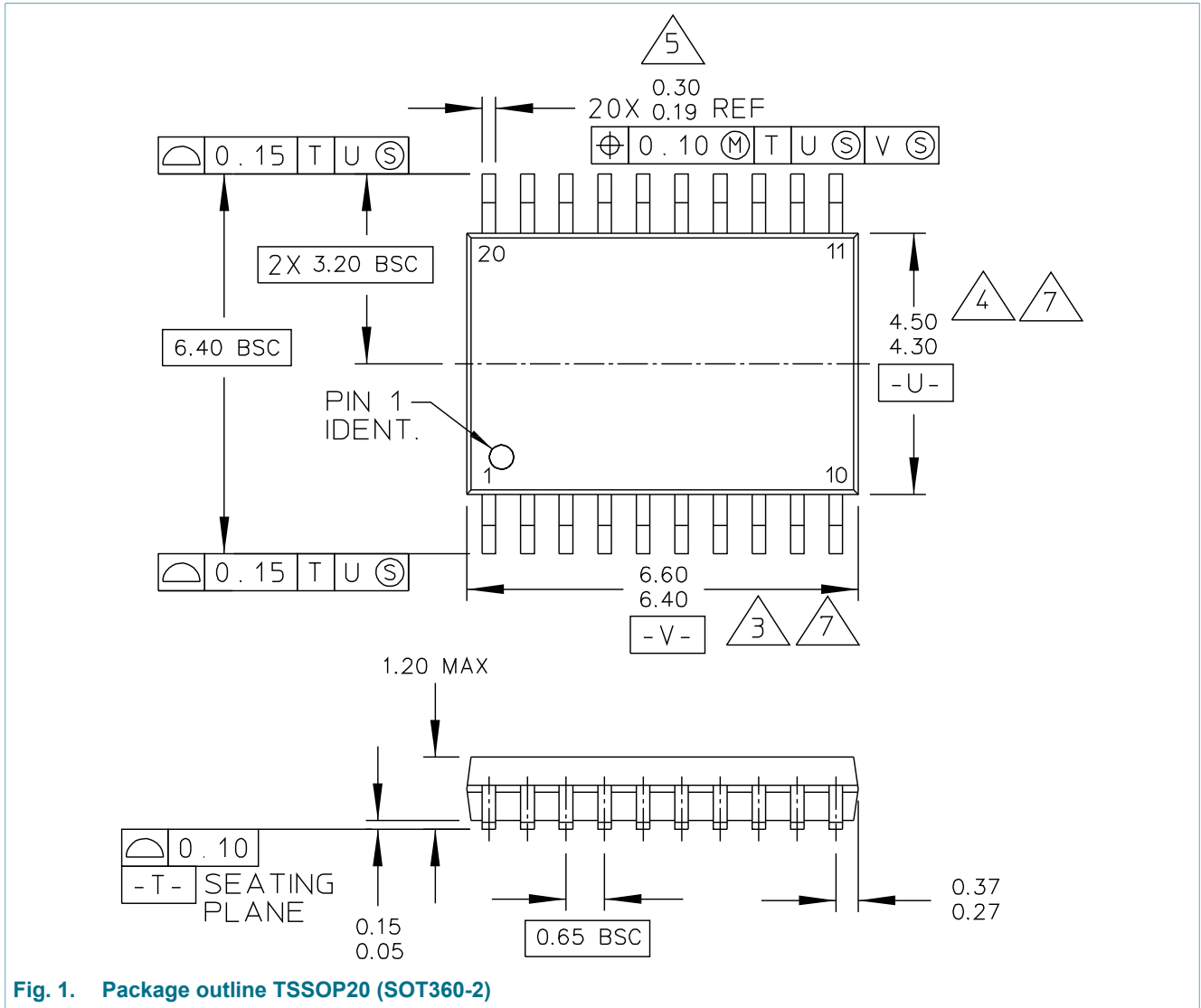


Fig. 1. Package outline TSSOP20 (SOT360-2)

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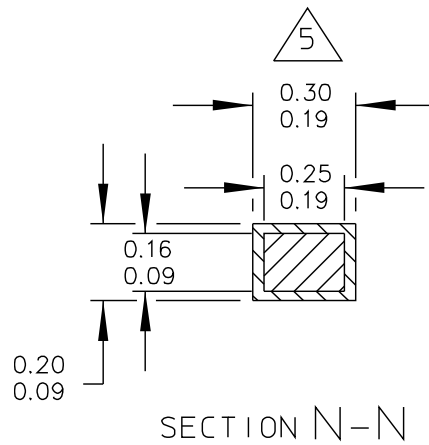


Fig. 2. Package outline dt1 TSSOP20 (SOT360-2)

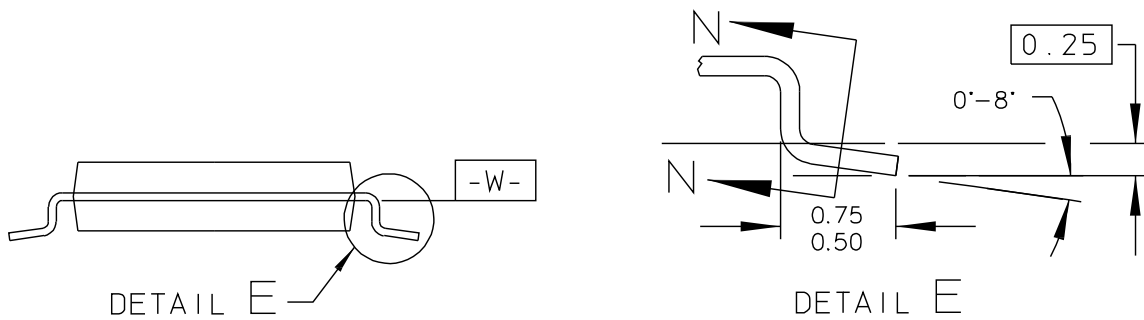


Fig. 3. Package outline dt2 TSSOP20 (SOT360-2)

NOTES:

1. CONTROLLING DIMENSION: MILLIMETER
2. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M-1982.
3. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSIONS ARE TO BE DETERMINED AT DATUM PLANE -W-.

Fig. 4. Package outline note TSSOP20 (SOT360-2)

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body

### 3. Legal information

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